

Manual Update Sheet

# **TMS320C5532/C5533/C5534/C5535 MicroStar BGA Discontinued and Redesigned**



## **ABSTRACT**

This document should be used in conjunction with the device data sheet and describes the updated package designator for the indicated devices.

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### **Trademarks**

MicroStar BGA™ and MicroStar Junior™ are trademarks of Texas Instruments.  
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## 1 Package Redesign Details

### Explanation

The devices in the MicroStar BGA™ packaging were redesigned using a laminate nfBGA package. This nfBGA package offers datasheet-equivalent electrical performance. It is also footprint equivalent to the MicroStar BGA. For more details, please refer to this [nfBGA Packaging Application Report](#).

When referencing the device data sheet, use the new package designator in place of the discontinued package designator throughout the document.

The orderable addendum at the end of the device data sheet will reflect the new package designator.

See the following page or the end of the device data sheet for the updated nfBGA package drawing.

**Table 1-1. Package Designator**

Old Package Designator	New Package Designator
ZHH	ZAY

### Reason for Discontinuance

Due to an equipment End-Of-Life notice from our substrate supplier, we are phasing out certain MicroStar BGA and MicroStar Junior™ BGA packaging devices and offering a Last Time Buy.

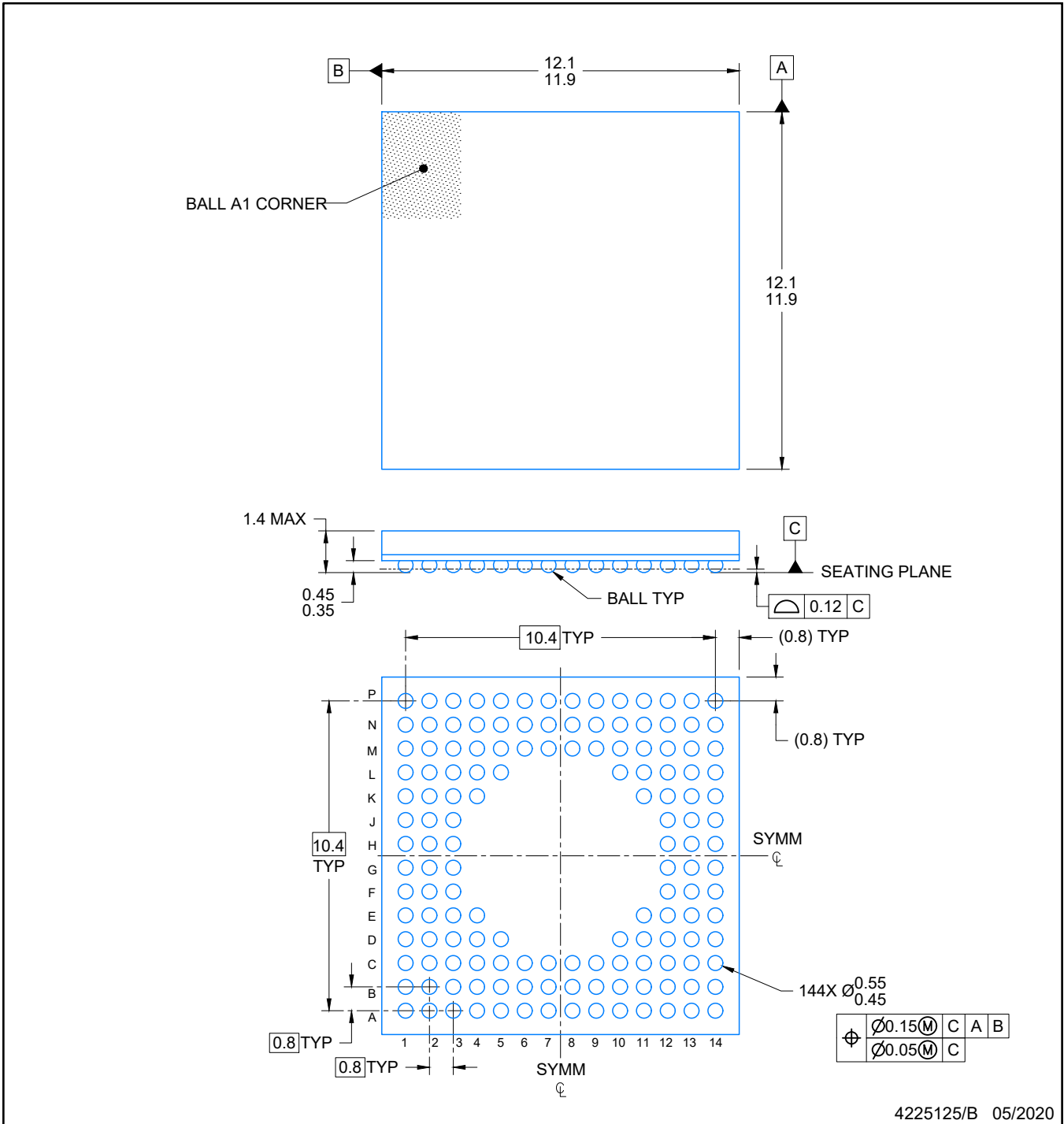
These devices have now been converted to an nfBGA package.

### Devices Affected

The following table describes the devices affected, the old and new package designators, and references to the device data sheet.

**Table 1-2. Devices and Nomenclature**

Device	Discontinued MicroStar BGA Device	Redesigned Laminate nfBGA Device	Device Data Sheet
TMS320C5532	TMS320C5532AZHH05	TMS320C5532AZAY05	SPRS737
	TMS320C5532AZHH10	TMS320C5532AZAY10	SPRS737
	TMS320C5532AZHHA05	TMS320C5532AZAYA05	SPRS737
	TMS320C5532AZHHA10	TMS320C5532AZAYA10	SPRS737
TMS320C5533	TMS320C5533AZHH05	TMS320C5533AZAY05	SPRS737
	TMS320C5533AZHH10	TMS320C5533AZAY10	SPRS737
	TMS320C5533AZHHA05	TMS320C5533AZAYA05	SPRS737
	TMS320C5533AZHHA10	TMS320C5533AZAYA10	SPRS737
TMS320C5534	TMS320C5534AZHH05	TMS320C5534AZAY05	SPRS737
	TMS320C5534AZHH10	TMS320C5534AZAY10	SPRS737
	TMS320C5534AZHHA05	TMS320C5534AZAYA05	SPRS737
	TMS320C5534AZHHA10	TMS320C5534AZAYA10	SPRS737
	TMS32C5534AZHHA05R	TMS32C5534AZAYA05R	SPRS737
TMS320C5535	TMS320C5535AZHH05	TMS320C5535AZAY05	SPRS737
	TMS320C5535AZHH10	TMS320C5535AZAY10	SPRS737
	TMS320C5535AZHHA05	TMS320C5535AZAYA05	SPRS737
	TMS320C5535AZHHA10	TMS320C5535AZAYA10	SPRS737

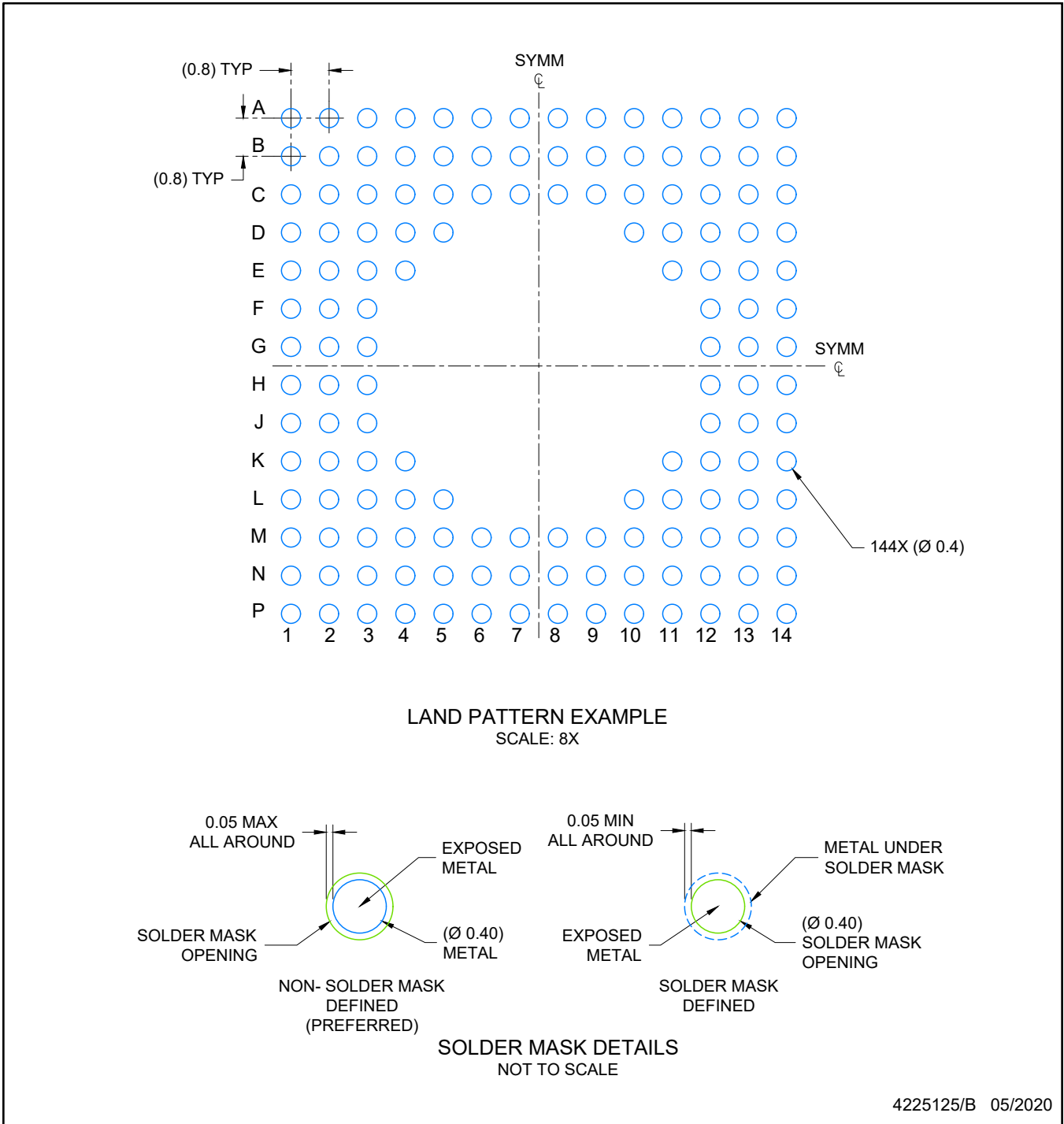


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NOTES:

NanoFree is a trademark of Texas Instruments.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



NOTES: (continued)

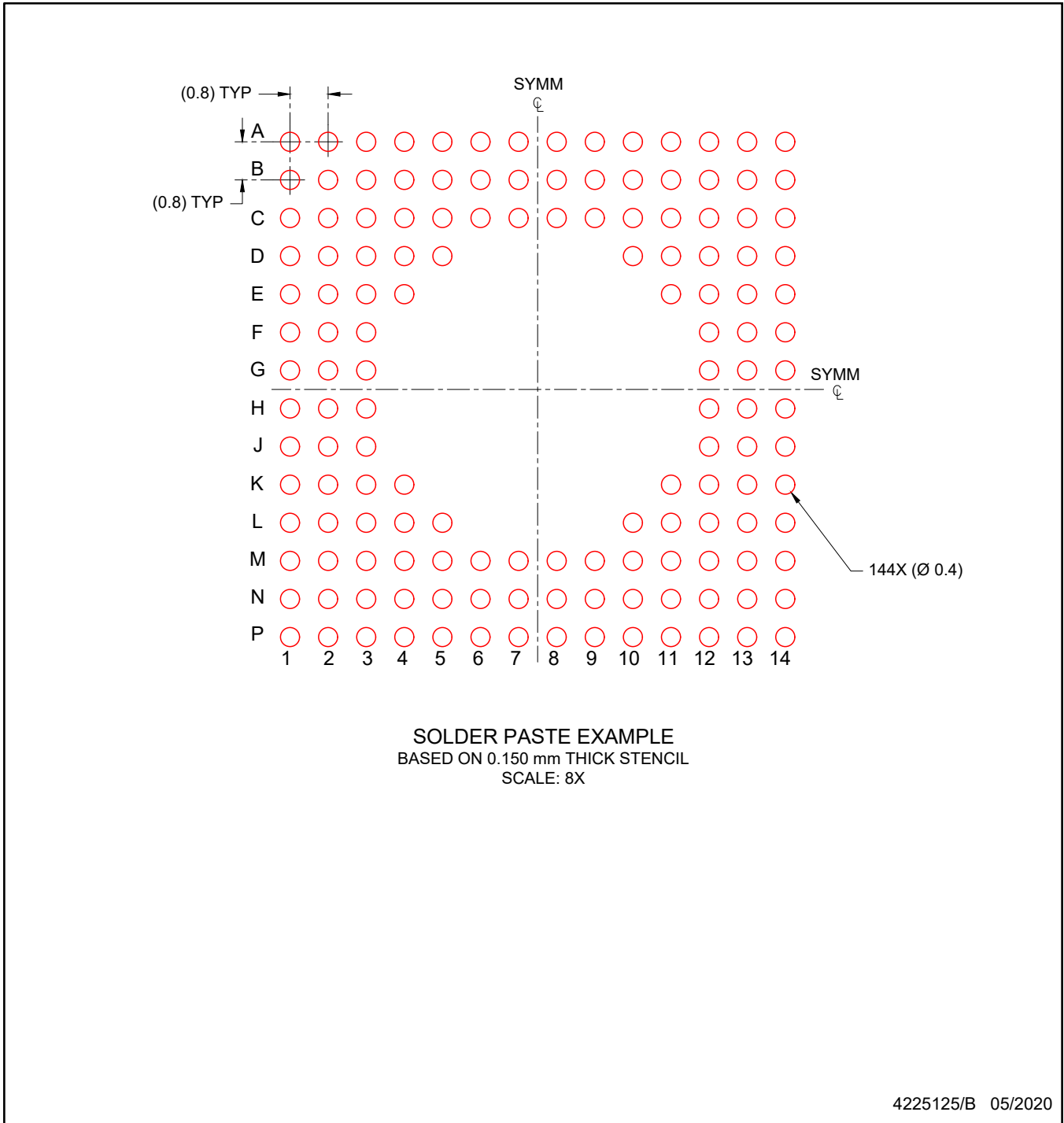
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. Refer to Texas Instruments Literature number SNVA009 ([www.ti.com/lit/snva009](http://www.ti.com/lit/snva009)).

# EXAMPLE STENCIL DESIGN

NFBGA - 1.4 mm max height

ZAY0144A

PLASTIC BALL GRID ARRAY



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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